<b>PCN Number:</b> 20220926		6000.1		PCN	N Date: September 28, 202				
Title: Qualification of new		w Fa	v Fab site (RFAB) using qualified Process Technology, Die Revision,						
1101	С.	and add	tional Ass	e mbl	ly & BOM options fo	r select	device	S	
Cus	stomer	Contact:		PCN	N Manager		Dept:		Quality Services
Proposed 1 <sup>st</sup> Ship Date:			Dec	Dec 28, 2022 Sample requests accepted until:		Oct 28, 2022*			
*Sa	*Sample requests received after Oct 28, 2022 will not be supported.								
Cha	ange Ty	/pe:							
$\boxtimes$	Assem	bly Site		$\boxtimes$	Assembly Process			Asse	mbly Materials
$\boxtimes$	Desigr	1			Electrical Specification			Mech	anical Specification
☐ Test Site			Packing/Shipping/Labeling			Test	Test Process		
☐ Wafer Bump Site				Wafer Bump Material			Wafe	Wafer Bump Process	
		X	Wafer Fab Materials			Wafe	r Fab Process		
				☐ Part number change			-		
	PCN Details								

### **Description of Change:**

Texas Instruments is pleased to announce the qualification of a new fab & process technology (RFAB, LBC9) and Assembly & BOM option for selected devices as listed below in the product affected section. Construction differences are noted below:

С	urrent Fab Site	•	A	dditional Fab S	ite
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
SFAB	HCMOS	150 mm	RFAB	LBC9	300 mm

The die was also changed as a result of the process change.

Additionally, there will be a BOM/Assembly options introduced for these devices:

## **Group 1: (RFAB/Process migration & BOM Update)**

	Current	Additional
Bond wire diameter (Cu)	0.96 mils	0.8 mils

# Group 2: (RFAB/Process migration BOM update at MLA & FMX as an alternate Assembly site)

	MLA Current	FMX Current	MLA New	FMX New
Bond wire diameter (Cu)	0.9 mil	0.96 mil	0.8 mil	0.8 mil
Mold Compound	4042503	4211880	4211880	4211880
Mount Compound	4042500	4147858	4147858	4147858
Lead Finish	NiPdAu	NiPdAu	NiPdAu	Matte Sn

# Group 3: (RFAB/Process migration, BOM Update in MLA & HFTF as an alternate Assembly site)

	MLA Current	FMX	MLA New	HFTF
Bond wire diameter (Cu)	0.96 mil	0.96 mil	0.8 mil	0.8 mil
Mount Compound	4147858	4147858	4147858	SID#A-03
Mold Compound	4211880	4211880	4211880	SID#R-30
Lead Finish	NiPdAu	NiPdAu	NiPdAu	Matte Sn

### **Group 4: (RFAB/Process migration & CDAT as alternate Assembly site)**

<b>3</b>			
	MLA	CDAT	
Bond wire diameter (Cu)	0.96 mil	0.8 mil	
Mold Compound	4208625	4222198	
Mount Compound	4205846	4207123	

# Group 5: (RFAB/Process migration, BOM update in MLA & TFME as an alternate Assembly site)

	MLA Current	ASESH	MLA New	TFME
Bond wire composition, diameter	Au or Cu, 0.96 mil	Cu, 1.0 mil	Cu, 0.8 mil	Cu, 0.8 mil
Mount Compound	4147858 or 4042500	SID#EY1000063	4147858	SID#A-03
Mold Compound	4206193 or 4211471	SID#EN2000508	4211471	SID#R-31
Lead Finish	NiPdAu	Matte Sn	NiPdAu	Matte Sn

# Group 6: (RFAB/Process migration BOM update in MLA & HFTF as an alternate Assembly site for select devices)

	MLA Current	MLA New	HFTF
Bond wire diameter (Cu)	0.96 mil	0.8 mil	0.8 mil
Mount Compound	4147858	4147858	SID#A-03
Mold Compound	4211880	4211880	SID#R-30
Lead Finish	NiPdAu	NiPdAu	Matte Sn

Upon expiry of this PCN TI will combine lead free solutions in a single <u>standard part number</u>, for the devices in group 3. For example; <u>CD74HC243M96</u> – can ship with both Matte Sn and NiPdAu/Ag.

#### Example:

- Customer order for 7500 units of CD74HC243M96 with 2500 units SPQ (Standard Pack Quantity per Reel).
- TI can satisfy the above order in one of the following ways.
  - I. 3 Reels of NiPdAu finish.
  - II. 3 Reels of Matte Sn finish
  - III. 2 Reels of Matte Sn and 1 reel of NiPdAu finish.
  - IV. 2 Reels of NiPdAu and 1 reel of Matte Sn finish.

#### Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-milimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

### **Impact on Environmental Ratings**

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
No Change	No Change     ■     No Change     ■     No Change     No Change     ■     No Change     ■     No Change     No Change	☑ No Change	⊠ No Change

### Changes to product identification resulting from this PCN:

#### **Fab Site Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
RFAB	RFB	USA	Richardson

### Die Rev:

 Current
 Ne w

 Die Rev [2P]
 Die Rev [2P]

 A, E, G, H, I, J, A, B

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
MLA	MLA	MYS	Kuala Lumpur
TI Mexico	MEX	MEX	Aguascalientes
ASESH	ASH	CHN	Shanghai
HFTFAT	HFT	CHN	Hefei
TFME	NF M	CHN	Economic Development Zone

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS

MADE IN: Malaysia 2DC: 2Q;

MSL '2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04

OPT: ITEM:

L: 5A (L)TO:1750



(1P) \$N74L\$07N\$R (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483812

(P) (2P) REV: (V) 0033317 (201) 890: SHE (211) CCO:USA (22L) ASO: MLA (23L) ACO: MYS

#### **Product Affected:**

### Group 1 Device list (RFAB/Process migration & BOM Update))

CD74HC245M96	SN74HC245DWRG4	CD74HC390E	CD74HCT259EE4
CD74HCT241M96	SN74HC640DWR	CD74HC390EE4	SN74HC393N
CD74HCT245M96	SN74HCT245DWR	CD74HC4511E	SN74HC4040N
CD74HCT540M96	SN74HCT245DWRE4	CD74HC4511EE4	SN74HC4040NE4
CD74HCT640E	SN74HCT245DWRG4	CD74HCT251E	SN74HCT138N
SN74HC245DWR	SN74HCT540DWR	CD74HCT259E	SN74HCT138NE4
SN74HC245DWRE4	SN74HCT540DWRG4		

# Group 2 Device list (RFAB/Process migration BOM update at MLA & FMX as an alternate Assembly site)

CD74HC147F	CD74HC4094F

# Group 3 Device list (RFAB/Process migration, BOM Update in MLA & HFTF as an alternate Assembly site)

SN74HC42DR

### **Group 4 Device list (RFAB/Process migration & CDAT as alternate Assembly site)**

SN74LV02ARGYR	SN74LV14ARGYR	SN74LV4T125RGYR	SN74LV74ARGYR
SN74LV125ATRGYR	SN74LV32ARGYR		

# Group 5 Device list (RFAB/Process migration, BOM update in MLA & TFME as an alternate Assembly site)

SN74LV08APWR	SN74LV14APWR	SN74LV32APWRG4	SN74LV74APWR
SN74LV08APWRG4	SN74LV14APWRG4	SN74LV4T125PWR	SN74LV74APWRG4
SN74LV11APWR	SN74LV32APWR		

# Group 6 Device list (RFAB/Process migration BOM update in MLA & HFTF as an alternate Assembly site for select devices)

CD74HC243M96	
( 1)/4H( /41M9h	

The following table provides the updated thermal characteristics to all devices contained within this PCN. All thermal values can be compared to the existing devices by reviewing the datasheets currently on TI.com. The impact to the customer system is anticipated to be negligible, however the customer must review their system design to assess any risk due to the change in thermal characteristics. Please see the table below which provides a summary of thermal values that some of the devices will be updated to based on each pin/pkg combination. The below table only applies to the following devices: CD74HC245M96, CD74HCT241M96, CD74HCT245M96, CD74HCT540M96, CD74HCT640E, SN74HC245DWR, SN74HC640DWR, SN74HCT245DWR, SN74HCT540DWR, SN74LV14APWR, SN74LV14APWRG4, SN74LV14ARGYR. The datasheets/thermal values for the other devices in this PCN will not be changed as a result of the changes in this PCN.

	THERMAL METRIC	PW (TSSOP)	RGY (VQFN) 14	DW (SOIC)	N (PDIP) 20	UNIT
		PINS	PINS	PINS	PINS	
RθJA	Junction-to-ambient thermal resistance	151.0	86.6	104.5	84.9	°C/W
RθJC(top)	Junction-to-case (top) thermal resistance	80.0	91.9	69.4	74.7	°C/W
RθJB	Junction-to-board thermal resistance	94.2	61.2	73.2	65.8	°C/W
ΤΙΨ	Junction-to-top characterization parameter	28.0	22.5	41.9	48.7	°C/W
ΨЈВ	Junction-to-board characterization parameter	93.6	61.1	72.6	65.5	°C/W
RθJĊ(bot)	Junction-to-case (bottom) thermal resistance	N/A	44.3	N/A	N/A	°C/W

TI Information Selective Disclosure

# Qualification Report Approve Date 06-SEPTEMBER-2022

#### **Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: CD74HCT241M96	Qual Device: SN74HCT540DWR	QBS Reference: SN74HCS273QPWRQ1	QBS Reference: SN74HCS74QDRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/135/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	3/231/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	3/30/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/3/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	3/90/0

- QBS: Qual By Similarity
- Qual Device CD74HCT241M96 is qualified at MSL1 260C
- Qual Device SN74HCT540DWR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- $\bullet \quad \text{The following are equivalent HTOL options based on an activation energy of 0.7eV:} \ 125\text{C}/1\text{k Hours}, \ 140\text{C}/480 \ \text{Hours}, \ 150\text{C}/300 \ \text{Hours}, \ \text{and} \ 155\text{C}/240 \ \text{Hours}, \ \text{Hours$
- $\bullet \quad \text{The following are equivalent HTSL options based on an activation energy of 0.7eV: } 150\text{C/1k Hours, and } 170\text{C/420 Hours} \\$
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2209-005

# Qualification Report Approve Date 07-SEPTEMBER-2022

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: CD74HC245M96	Qual Device: SN74HC245DWR	Qual Device: CD74HCT245M96	Qual Device: SN74HCT245DWR	Qual Device: SN74HC640DWR	Qual Device: CD74HC243M96	Qual Device: CD74HC243M96	Qual Device: SN74HC42DR	Qual Device: SN74HC42DR	QBS Reference: SN74HCS174DR
HAST	A2	Biased HAST	130C	96 Hours	-	-	-	-	-	-	-	-	-	3/231/0
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	-	-	-	-
UHAST	А3	Unbiased HAST	130C	96 Hours	-	-	-	-	-	-	-	-	-	3/231/0
UHAST	А3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	-	-	-	-
TC	A4	Temperature Cycle	-65/150C	500 Cycles	-	1/77/0	-	-	-	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	1/77/0	-	-	-	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	-	-	-	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours		•		-				-		
HTSL	A6	High Temperature Storage Life	170C	420 Hours		-		-		-	-	-	-	3/231/0
HTOL	B1	Life Test	125C	1000 Hours		-	-	-	-	-	-	-	-	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	-	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	-	-	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	1/3/0	1/3/0	-	1/3/0	1/3/0	-	1/3/0	-	3/9/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	-	-	-	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	1/3/0	1/3/0	-	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	1/3/0	1/3/0	-	1/3/0	-	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp		-	-	-	-	1/30/0	-	-	-	-	3/90/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters		-	-	-	-	1/30/0	1/30/0	-	1/30/0	-	3/90/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	-	-	-	-	-	-

- QBS: Qual By Similarity
  Qual Device CD74HC245M99 is qualified at MSL1 260C
  Qual Device SN74HC245M97 is qualified at MSL1 260C
  Qual Device CD74HC7245DWR is qualified at MSL1 260C
  Qual Device SN74HC745DWR is qualified at MSL1 260C
  Qual Device SN74HC462M97 is qualified at MSL1 260C
  Qual Device CD74HC243M98 is qualified at MSL1 260C
  Qual Device CD74HC243M98 is qualified at MSL1 260C
  Qual Device SN74HC42DR is qualified at MSL1 260C
  Qual Device SN74HC42DR is qualified at MSL1 260C
  Qual Device SN74HC42DR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Blased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
  The following are equivalent HTDL optons based on an activation energy of 0.7eV: 125C/1k Hours, 140C/490 Hours, 150C/300 Hours, and 155C/240 Hours
  The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
  The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green TI Qualification ID: R-NPD-2204-113

# Qualification Report Approve Date 01-SEPTEMBER-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: CD74HC147E	Qual Device: CD74HC147E	Qual Device: CD74HC4094E	Qual Device: CD74HC4094E	Qual Device: CD74HCT640E	QBS Reference: <u>SN74HC595N</u>	QBS Reference: <u>TLC339IN</u>	QBS Reference: SN74HCS74QPWRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	-	3/231/0
UHAST	А3	Autoclave	121C/15psig	96 Hours	-	-	-	-	-	3/231/0	3/231/0	-
UHAST	А3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	-	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	-	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	-	-	3/135/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	-	3/231/0	3/231/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	-	-	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	-	-	3/2400/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	-	-	-	3/30/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	1/3/0	-	1/3/0	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	1/3/0	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	1/3/0	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	1/30/0	1/30/0	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	-	-	-	3/90/0

- QBS: Qual By Similarity
   Qual Device CD74HC147E is qualified at MSL1 260C
   Qual Device CD74HC147E is qualified at MSL1 260C
- Qual Device CD74HC4094E is qualified at MSL1 260C
   Qual Device CD74HC4094E is qualified at MSL1 260C
- Qual Device CD74HCT640E is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/lk Hours, and 170C/420 Hours
  The following are equivalent Temp Cycle options per JESD47 : -55C/l25C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-NPD-2204-118

## Qualification Report Approve Date 20-September-2022

### Data Displayed as: Number of lots / Total sample size / Total failed

_															
Туре	#	Test Name	Condition	Duration	Qual Device: SN74LV02ARGYR	Qual Device: SN74LV125ATRGYR	Qual Device: SN74LV14ARGYR	Qual Device: SN74LV32ARGYR	Qual Device: SN74LV4T125RGYR	Qual Device: SN74LV74ARGYR	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: PCM6260QRTVRQ1	QBS Reference: TS3A5017QRGYRQ1		
HAST	A2	Biased HAST	130C/85%RH	96 Hours							3/231/0	3/231/0	3/231/0		
UHAST	А3	Autoclave	121C/15psig	96 Hours	-	-	-	-	-	-	-	-	3/231/0		
UHAST	А3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-		-	3/231/0	3/231/0	-		
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	-	-	3/231/0	3/231/0	-		
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-		-	3/231/0	3/231/0	3/231/0		
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	-	3/2400/0	3/2400/0	-		
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	-	-	1/76/0	-	-	-	-		
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	-	1/76/0	-	-	-	-		
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	-	-	3/30/0	3/30/0	3/30/0		
ESD	E2	ESD CDM	-	1500 Volts	1/3/0	-	-	-	-	-	-	-	1/3/0		
ESD	E2	ESD HBM	-	4000 Volts	1/3/0	-	-	-	-	-	1/3/0	1/3/0	1/3/3		
LU	E4	Latch-Up	Per JESD78		1/3/0	-	-	-	-	-	-	-	-		
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	-	-	3/90/0	3/90/0	3/90/0		

- QBS: Qual By Similarity
   Qual Device SN74LV02ARGYR is qualified at MSL1.280C
   Qual Device SN74LV12ASTRGYR is qualified at MSL1.280C
   Qual Device SN74LV12ARGYR is qualified at MSL1.280C
   Qual Device SN74LV12ARGYR is qualified at MSL1.280C
   Qual Device SN74LV12ARGYR is qualified at MSL1.280C
   Qual Device SN74LV712ARGYR is qualified at MSL1.280C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Blased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
  The following are equivalent HTCL options based on an activation energy of 0.7 eV: 1250/Lk Hours, 1400/L809 Hours, 1500/300 Hours, and 1550/240 Hours
  The following are equivalent HTSL options based on an activation energy of 0.7 eV: 1500/Lk Hours and 1700/L420 Hours
  The following are equivalent Temp Cycle options per JESD47: -550/1250/700 Cycles and -650/1500/5000 Cycles
  The following are equivalent Temp Cycle options per JESD47: -550/1250/700 Cycles and -650/1500/5000 Cycles

  The following are equivalent Temp Cycle options per JESD47: -550/1250/700 Cycles and -650/1500/5000 Cycles

  The following are equivalent Temp Cycle options per JESD47: -550/1250/700 Cycles and -650/1500/5000 Cycles

  The following are equivalent Temp Cycle options per JESD47: -550/1250/700 Cycles and -650/1500/5000 Cycles

  The following are equivalent Temp Cycle options per JESD47: -550/1250/700 Cycles and -650/1500/5000 Cycles

  The following are equivalent Temp Cycle options per JESD47: -550/1250/700 Cycles and -650/1500/5000 Cycles

  The following are equivalent Temp Cycle options per JESD47: -550/1250/700 Cycles and -650/1500/5000 Cycles

  The following are equivalent Temp Cycle options per JESD47: -550/1250/700 Cycles and -650/1500/5000 Cycles

  The following are equivalent Temp Cycle options per JESD47: -550/1250/700 Cycles and -650/150/1500/700 Cycles

  The following are equivalent Temp Cycle options per JESD47: -550/1250/700 Cycles and -650/150/1500/700 Cycles

  The following are equivalent Temp Cycle options per JESD47: -550/1250/700 Cycles and -650/150/1500/700 Cycles

  The following are equivalent Temp Cycle options are the following are equivalent Temp Cycles options are the following are equi

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

#### Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-NPD-2111-093

#### Qualification Report Approve Date 21-SEPTEMBER-2022

#### Qualification Results

#### Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>SN74LV4T125PWR</u>	QBS Reference: <u>SN74HCS74QPWRQ1</u>	QBS Reference: <u>SN74HCS74PWR</u>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	1/77/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	3/30/0	3/15/0
ESD	E2	ESD CDM	-	1500 Volts	1/3/0	1/3/0	3/9/0
ESD	E2	ESD HBM	-	4000 Volts	-	1/3/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	3/90/0	3/90/0

- · QBS: Qual By Similarity
- Qual Device SN74LV00APWR is qualified at MSL1 260C
- Qual Device SN74LV04APWR is qualified at MSL1 260C
- Qual Device SN74LV02APWR is qualified at MSL1 260C
- Qual Device SN74LV05APWR is qualified at MSL1 260C
- Qual Device SN74LV06APWR is qualified at MSL1 260C
- Qual Device SN74LV07APWR is qualified at MSL1 260C
- Qual Device SN74LV07APWRG3 is qualified at MSL1 260C
- Qual Device SN74LV08APWR is qualified at MSL1 260C
- Qual Device SN74LV10APWR is qualified at MSL1 260C
   Oual Device SN74LV11APWR is qualified at MSL1 260C
- Qual Device SN74LV125APWR is qualified at MSL1 260C
- Qual Device SN74LV126APWR is qualified at MSL1 260C
- Qual Device SN74LV132APWR is qualified at MSL1 260C
- Qual Device SN74LV14APWR is qualified at MSL1 260C
- Qual Device SN74LV20APWR is qualified at MSL1 260C
- Qual Device SN74LV21APWR is qualified at MSL1 260C
- Qual Device SN74LV27APWR is qualified at MSL1 260C
- Qual Device SN74LV32APWR is qualified at MSL1 260C
   Qual Device SN74LV74APWR is qualified at MSL1 260C
- Qual Device SN74LV74AFWR is qualified at MSL1 260C
   Qual Device SN74LV86APWR is qualified at MSL1 260C
- Qual Device SN74LV4T125PWR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
   The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
  - The following are equivalent temp by the epitons per trees 41 . Societies by the byte between the

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

#### Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-NPD-2111-095

### Qualification Report Approve Date 03-AUGUST -2022

#### **Qualification Results**

#### Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: CD74HCT251E			Qual Device: CD74HC4511E		Qual Device: CD74HC4511E	Qual Device: SN74HC393N
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	1/3/0	1/3/0	-	-	-

- · QBS: Qual By Similarity
- Qual Device CD74HCT251E is qualified at MSL1 NOT CLASSIFIED
- Qual Device CD74HCT259E is qualified at MSL1 NOT CLASSIFIED
- Qual Device SN74HC393N is qualified at MSL1 NOT CLASSIFIED
- Oual Device CD74HC4511E is qualified at MSL1 NOT CLASSIFIED.
- Qual Device CD74HCT251E is qualified at MSL1 NOT CLASSIFIED
- Qual Device CD74HC4511E is qualified at MSL1 NOT CLASSIFIED
- Qual Device SN74HC393N is qualified at MSL1 NOT CLASSIFIED
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2112-033

Ti Information

#### Qualification Report Approve Date 22-SEPTEMBER-2022

#### Qualification Results

### Data Displayed as: Number of lots / Total sample size / Total failed

Туре		Test Name	Condition	Duration	Qual Device: SN74LV08APWR	Qual Device: SN74LV08APWRG4	Qual Device: SN74LV11APWR	Qual Device: SN74LV14APWR	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74LV08ATPWRG4Q1	QBS Reference: SN74LV11ATPWRG4Q1	QBS Reference: SN74LV14ATPWRQ1	QBS Reference: SN74LV32ATPWRG4Q1	QBS Reference: SN74LV74AQPWRG4Q1	QBS Reference: ADS131B04QPWRQ1
HAST	A2	Blased HAST	130C/85%RH	96 Hours	-	-		-	3/231/0				-		3/231/0
UHAST	А3	Unblased HAST	130C/85%RH	96 Hours	-				3/231/0				-		3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	-	-		-	-		3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours		-			3/135/0	-		-	-		
HTOL	81	Life Test	125C	1000 Hours	-				3/231/0						
HTOL	81	Life Test	150C	300 Hours	-	-	-	-	-	-	-	1/77/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0	-		-	-		-
PD	C4	Physical Dimensions	Cpk>1.67	-	-				3/30/0				-		•
ESD	E2	ESD CDM		1500 Volts	-	-		-	1/3/0			1/3/0	-	1/3/0	-
ESD	E2	ESD HBM		4000 Volts	-	-		-	1/3/0	-		1/3/0	-	1/3/0	1/3/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	3/90/0	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	3/90/0

- QBS: Qual By Similarity
- Qual Device SN74LV08APWR is qualified at MSL1 260C
   Qual Device SN74LV08APWRG4 is qualified at MSL1 260
- Qual Device SN74LV11APWR is qualified at MSL1 2600
   Qual Device SN74LV14APWR is qualified at MSL1 2600
- Qual Device SN74LV14APWRG4 is qualified at MSL1 260
   Qual Device SN74LV32APWR is qualified at MSL1 260C
- Qual Device SN74LV32APWRG4 is qualified at MSL1 260
- Qual Device SN74LV74APWR is qualified at MSL1 260C
   Qual Device SN74LV74APWR is qualified at MSL1 260C
   Qual Device SN74LV74APWRG4 is qualified at MSL1 260C
- Qual Device SN74LV74APWRG4 is qualified at MSL1 260
   Qual Device SN74LV86APWR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Blased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
   The following are equivalent HTGL options based on an activation energy of 0.7eV : 125C/JR Hours, 140C/JRD Hours, 150C/JRD Hours, and 155C/JRD Hours.
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 H
   The following are equivalent 7emp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/600 Cycles

Quality and Environmental data is available at Tr's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Ti Qualification ID: R-NPD-2111-101

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN www admin team@list.ti.com

## **IMPORTANT NOTICE AND DISCLAIMER**

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disdaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (<a href="www.ti.com/legal/termsofsale.html">www.ti.com/legal/termsofsale.html</a>) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.